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[10191/1629]

REPLY UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP ART UNIT 1765

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6/12/03

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s) : Franz LAERMER et al.  
Serial No. : 09/720,761  
Filed : March 26, 2001  
For : METHOD OF PLASMA ETCHING OF SILICON  
Examiner : Kin Chan Chen  
Art Unit : 1765  
Confirmation No. : 5642

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450 on:

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Signature: Richard L. Mayer  
Richard L. Mayer

**Mail Stop AF**  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

**REPLY UNDER 37 C.F.R. 1.116**

S I R:

This paper addresses the Final Office Action dated April 10, 2003 in connection with the above-captioned application.

**REMARKS**

**I. Introduction**

Claims 19 to 36 are pending in the present application. In view of the following remarks, it is respectfully submitted that all of the presently pending claims are allowable, and reconsideration is respectfully requested.

**II. Rejection of Claims 19 to 22 and 24 to 27 Under 35 U.S.C. § 103(a)**

Claims 19 to 22 and 24 to 27 were rejected under 35 U.S.C. § 103(a) as unpatentable over Journal of the Electrochemical Society, Dec. 1982, USA Bd 129, Nr. 12, Pages 2755 to 2760 ("Flamm et al."). Applicants respectfully submit that Flamm et al. do not render obvious claims 19 to 22 and 24 to 27 for the following reasons.